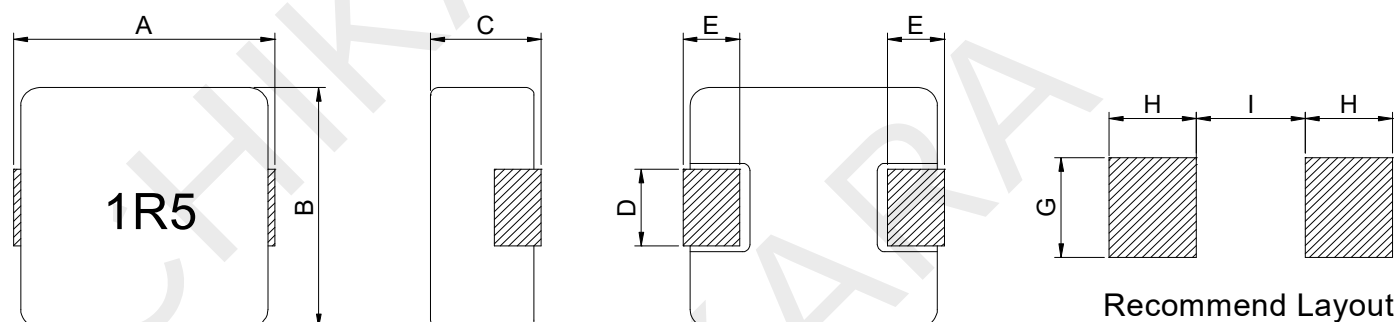


Features

- High energy storage and very low resistance
- Storage temperature range:-55°C to +125°C
- Operating temperature range:-55°C to +125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:400pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	G	H	I
13.3±0.5	12.6±0.4	6.0Max.	See table	2.5±0.5	6.0	3.25	8.0

Part Number Description

SP14 - 138060 1R5 M
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic



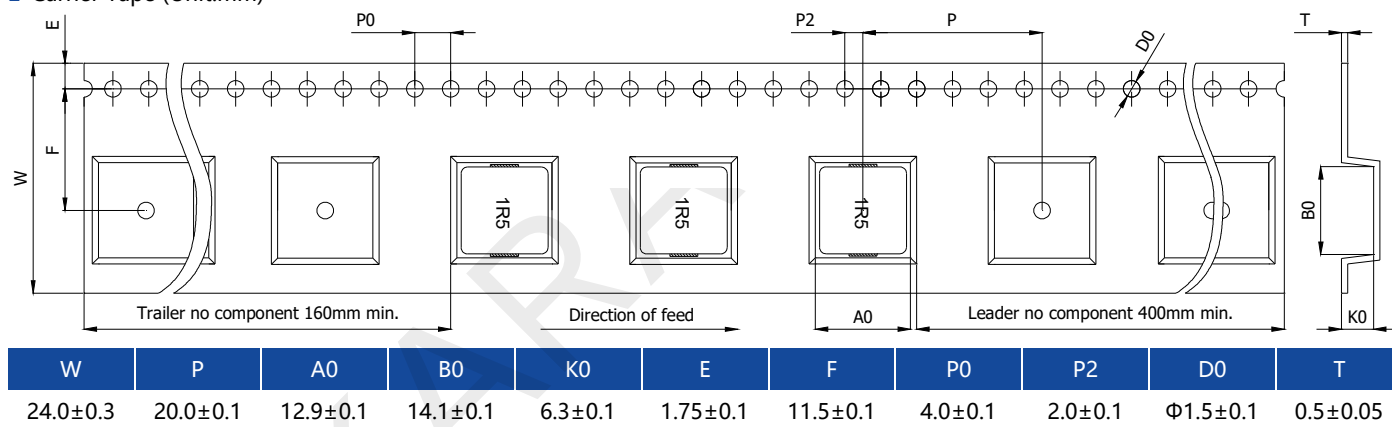
Electrical Characteristic

Part Number	Inductance L0(uH)	DCR (mΩ)Typ.	DCR (mΩ)Max.	SRF (MHz)Typ.	Isat (A)Typ.	Irms (A)Typ.	D (mm)±0.5
SP14-1380601R5M	1.5±20%	2.50	2.90	35.0	30.0	27.0	3.3
SP14-1380602R2M	2.2±20%	3.40	4.20	33.0	28.0	22.0	3.3
SP14-1380603R3M	3.3±20%	5.50	6.80	27.0	25.0	17.0	4.7
SP14-1380604R7M	4.7±20%	6.90	9.00	22.0	24.0	15.0	4.7
SP14-1380605R6M	5.6±20%	8.50	11.0	19.5	22.5	13.0	4.7
SP14-1380606R8M	6.8±20%	11.6	13.5	17.0	19.0	12.0	4.7
SP14-1380608R2M	8.2±20%	13.0	16.0	15.0	13.5	11.0	4.7
SP14-138060100M	10±20%	18.0	20.7	13.2	12.5	10.0	4.7
SP14-138060120M	12±20%	20.0	23.0	11.8	10.0	9.0	4.7
SP14-138060150M	15±20%	24.0	29.0	10.0	9.0	8.5	4.7
SP14-138060180M	18±20%	28.0	35.0	8.5	8.0	7.5	4.7
SP14-138060220M	22±20%	30.0	39.5	7.2	7.5	7.0	4.7
SP14-138060270M	27±20%	46.5	56.0	6.5	6.5	6.0	4.7
SP14-138060330M	33±20%	55.0	75.0	6.0	6.0	5.5	4.7
SP14-138060470M	47±20%	76.0	90.0	5.0	5.5	5.0	4.7
SP14-138060680M	68±20%	110	140	4.5	4.5	4.0	4.7
SP14-138060101M	100±20%	170	200	3.8	3.5	3.0	4.7
SP14-138060121M	120±20%	190	235	3.2	3.2	2.0	4.7
SP14-138060151M	150±20%	295	350	2.5	2.7	1.5	4.7

- Test frequency and voltage:100KHz,1Vrms.
- All test data referenced to 25°C ambient.
- Absolute maximum voltage: 50Vdc.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It's suggested to verify the temperature rise of the component under the real operation application conditions.

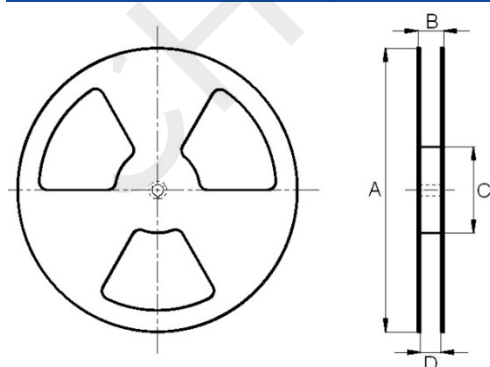
Packaging Specification

■ Carrier Tape (Unit:mm)



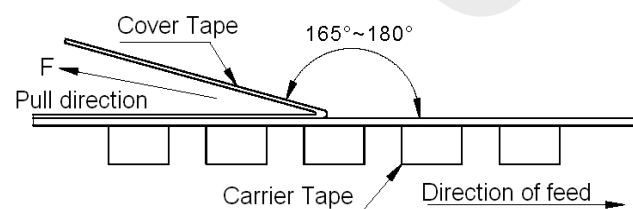
■ Reel (Unit:mm)

A	B	C	D
Φ330±1.0	28.9Max.	Φ100±1.0	24.5±0.5



■ Taping Method

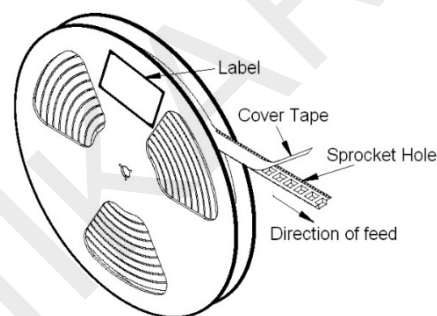
Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.3N	165°~180°	300mm/min.



※ Packing is referred to the international standard IEC 60286-3.

■ Package Quantity

Parts per reel
400Pcs



Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.